| L Number | Hits | Search Text | DB | Time stamp |
|---|---|---|---|---|
| 1 | 292878 | conferenc$3 teleconferenc$3 meeting collaborat$3 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 20:27 |
| 2 | 254032 | login log-in password (access$3 near3 (control permi$5 security)) authenticat$3 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 20:29 |
| 3 | 2868995 | conferee participant member | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 20:30 |
| 4 | 9975 | (login log-in password (access$3 near3 (control permi$5 security)) authenticat$3) with (conferee participant member) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 20:31 |
| 5 | 39218 | (material document project) with ((conferenc$3 teleconferenc$3 meeting collaborat$3) discussion) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 20:32 |
| 6 | 125156 | (material document project) same (design$3 manufacturing fabricat$3 product performance evaluation) same (semiconductor chip ic (integrated adj1 circuit)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 21:37 |
| 7 | 7 | (conferenc$3 teleconferenc$3 meeting collaborat$3) and ((login log-in password (access$3 near3 (control permi$5 security)) authenticat$3) with (conferee participant member)) and ((material document project) with ((conferenc$3 teleconferenc$3 meeting collaborat$3) discussion)) and ((material document project) same (design$3 manufacturing fabricat$3 product performance evaluation) same (semiconductor chip ic (integrated adj1 circuit))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 20:35 |
| 8 | 1554962 | (material document project) same (design$3 manufacturing fabricat$3 product performance evaluation) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 20:40 |
| 9 | 1313 | (conferenc$3 teleconferenc$3 meeting collaborat$3) and (login log-in password (access$3 near3 (control permi$5 security)) authenticat$3) and (conferee participant member) and ((material document project) with ((conferenc$3 teleconferenc$3 meeting collaborat$3) discussion)) and ((material document project) same (design$3 manufacturing fabricat$3 product performance evaluation) ) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 20:41 |
| 10 | 766007 | (design$3 manufacturing fabricat$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 21:09 |

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|---|---|---|---|---|
| 11 | 431 | ((conferenc$3 teleconferenc$3 meeting collaborat$3) and (login log-in password (access$3 near3 (control permi$5 security)) authenticat$3) and (conferee participant member) and ((material document project) with ((conferenc$3 teleconferenc$3 meeting collaborat$3) discussion)) and ((material document project) same (design$3 manufacturing fabricat$3 product performance evaluation) )) and ((design$3 manufacturing fabricat$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 20:43 |
| 12 | 307 | (((conferenc$3 teleconferenc$3 meeting collaborat$3) and (login log-in password (access$3 near3 (control permi$5 security)) authenticat$3) and (conferee participant member) and ((material document project) with ((conferenc$3 teleconferenc$3 meeting collaborat$3) discussion)) and ((material document project) same (design$3 manufacturing fabricat$3 product performance evaluation) )) and ((design$3 manufacturing fabricat$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit)))) and sale | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 20:45 |
| 13 | 52 | ((((conferenc$3 teleconferenc$3 meeting collaborat$3) and (login log-in password (access$3 near3 (control permi$5 security)) authenticat$3) and (conferee participant member) and ((material document project) with ((conferenc$3 teleconferenc$3 meeting collaborat$3) discussion)) and ((material document project) same (design$3 manufacturing fabricat$3 product performance evaluation) )) and ((design$3 manufacturing fabricat$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit)))) and sale) and chat | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 20:45 |
| 14 | 52 | ((((conferenc$3 teleconferenc$3 meeting collaborat$3) and (login log-in password (access$3 near3 (control permi$5 security)) authenticat$3) and (conferee participant member) and ((material document project) with ((conferenc$3 teleconferenc$3 meeting collaborat$3) discussion)) and ((material document project) same (design$3 manufacturing fabricat$3 product performance evaluation) )) and ((design$3 manufacturing fabricat$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit)))) and sale) and (chat chatroom) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 21:39 |
| 15 | 52 | (((((conferenc$3 teleconferenc$3 meeting collaborat$3) and (login log-in password (access$3 near3 (control permi$5 security)) authenticat$3) and (conferee participant member) and ((material document project) with ((conferenc$3 teleconferenc$3 meeting collaborat$3) discussion)) and ((material document project) same (design$3 manufacturing fabricat$3 product performance evaluation) )) and ((design$3 manufacturing fabricat$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit)))) and sale) and (chat chatroom)) and (link$3 hyperlink$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 21:05 |
| 16 | 0 | 20040205644.URPN. | USPAT | 2004/11/07 21:05 |

| 17 | 36 | ((("20020156929") or ("20040205644") or ("20040107256") or ("20040107249") or ("20040107125") or ("20040103040") or ("20030192029") or ("20030154387") or ("20030152904") or ("20030126033") or ("20030120557") or ("20030023686") or ("20020184191") or ("20010042030") or ("6615166") or ("6611822") or ("6581039") or ("6571235") or ("5867494")).PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 21:09 |
| 18 | 21 | (((("20020156929") or ("20040205644") or ("20040107256") or ("20040107249") or ("20040107125") or ("20040103040") or ("20030192029") or ("20030154387") or ("20030152904") or ("20030126033") or ("20030120557") or ("20030023686") or ("20020184191") or ("20010042030") or ("6615166") or ("6611822") or ("6581039") or ("6571235") or ("5867494")).PN.) and ((design$3 manufacturing fabricat$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 21:09 |
| 19 | 3577 | (conferenc$3 teleconferenc$3 meeting collaborat$3) same ((design$3 manufacturing fabricat$3 product performance evaluation) with (semiconductor chip ic (integrated adj1 circuit))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 21:38 |
| 20 | 3560 | (conferenc$3 teleconferenc$3 meeting collaborat$3) with ((design$3 manufacturing fabricat$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 21:38 |
| 21 | 4959 | ((conferenc$3 teleconferenc$3 meeting collaborat$3) same ((design$3 manufacturing fabricat$3 product performance evaluation) with (semiconductor chip ic (integrated adj1 circuit)))) ((conferenc$3 teleconferenc$3 meeting collaborat$3) with ((design$3 manufacturing fabricat$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit)))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 21:39 |
| 22 | 14 | (((conferenc$3 teleconferenc$3 meeting collaborat$3) same ((design$3 manufacturing fabricat$3 product performance evaluation) with (semiconductor chip ic (integrated adj1 circuit)))) ((conferenc$3 teleconferenc$3 meeting collaborat$3) with ((design$3 manufacturing fabricat$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit))))) and (chat chatroom) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/11/07 21:39 |